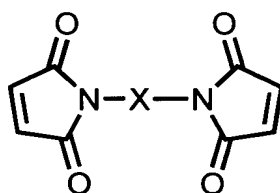


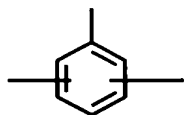
WHAT IS CLAIMED

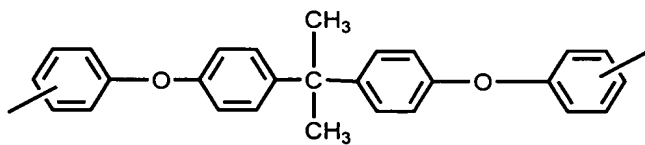
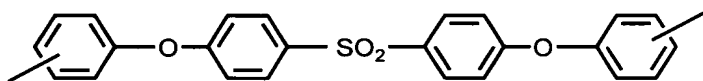
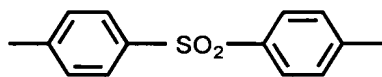
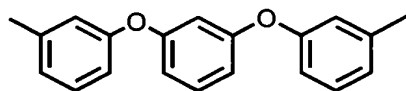
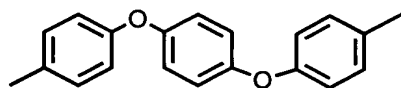
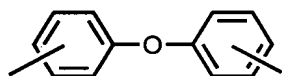
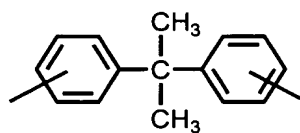
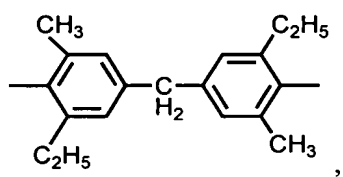
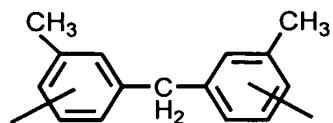
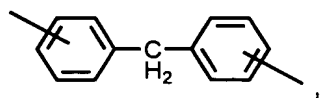
1. A method for improving the cohesive strength at elevated temperature of a die attach adhesive formulation of a liquid curable resin or a combination of curable resins, initiator, and filler, comprising adding to the adhesive formulation an aromatic bismaleimide resin powder that does not dissolve in the curable resin.
2. The method according to claim 1 in which the elevated temperature is 260°C or less.
3. The method according to claim 1 in which the bismaleimide is present in an amount from greater than 3 weight percent to about 30 weight percent.
4. The method according to claim 1 in which the bismaleimide has the structure

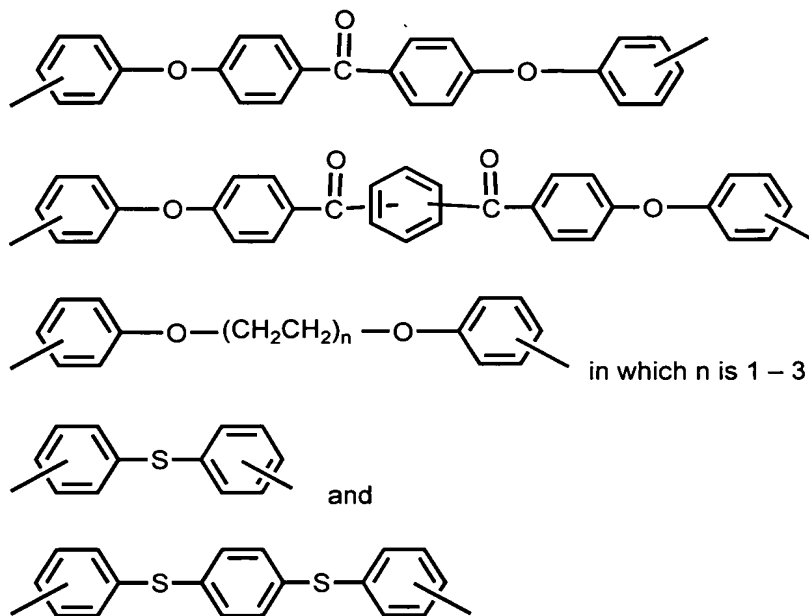


in which X is an aromatic group.

5. The method according to claim 4 in which X is selected from the group consisting of:

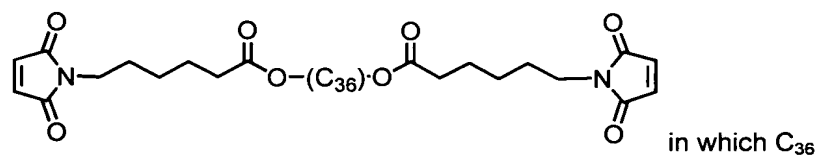




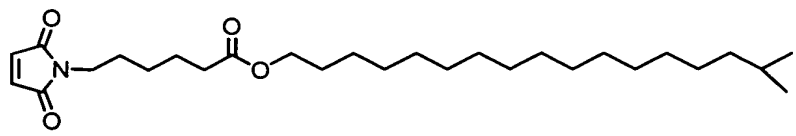


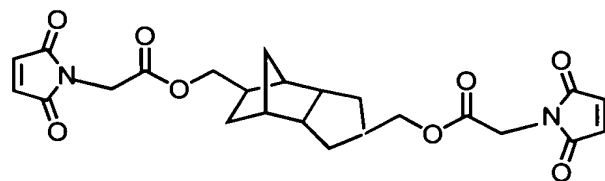
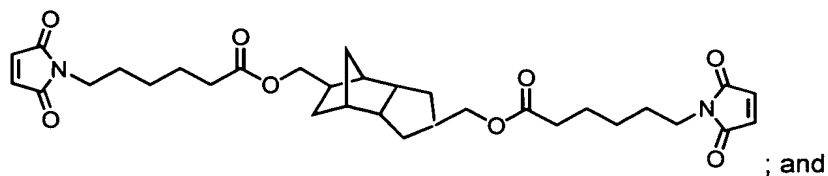
6. The method according to claim 1 in which the curable resin is a maleimide resin, a cyanate ester resin, an acrylate resin, or a combination of those resins.

7. The method according to claim 6 in which the maleimide resin is selected from the group consisting of



represents a linear or branched chain (with or without cyclic moieties) of 36 carbon atoms;





8. The method according to claim 6 in which the acrylate resin is selected from the group consisting of isobornyl acrylate, isobornyl methacrylate, lauryl acrylate, lauryl methacrylate, poly(butadiene) with acrylate functionality and poly(butadiene) with methacrylate functionality.